

### General Description

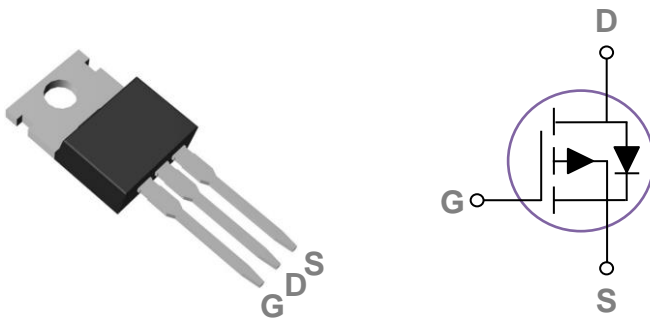
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
-100V	41mΩ	-35A

### Features

- -100V,-35A, RDS(ON) 41mΩ@VGS = -10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### TO220 Pin Configuration



### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	-35	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	-22	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-140	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	180	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	-60	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	142	W
	Power Dissipation – Derate above 25°C	1.14	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	0.88	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-100	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-80V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	μA
		V <sub>DS</sub> =-80V, V <sub>GS</sub> =0V, T <sub>J</sub> =85°C	---	---	-10	μA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-15A	---	34	41	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A	---	44	57	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250μA	-1.2	-1.6	-2.5	V

**Dynamic and switching Characteristics<sup>3</sup>**

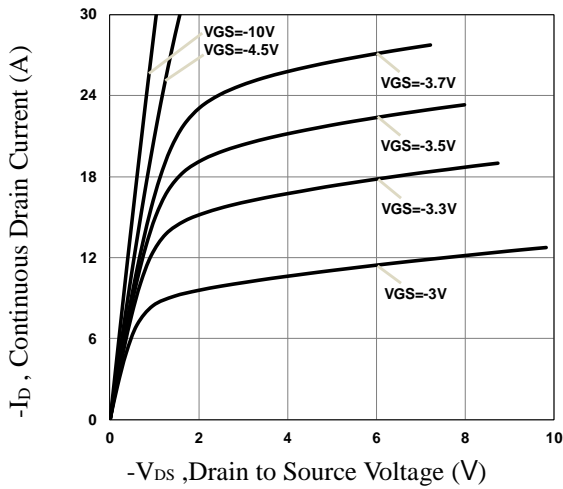
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-50V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-15A	---	22	35	nC
			---	11	16.5	
			---	1	3	
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =-50V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-15A	---	4.4	7	ns
Q <sub>gd</sub>	Gate-Drain Charge		---	5	8	
T <sub>d(on)</sub>	Turn-On Delay Time		---	6	10	
T <sub>r</sub>	Rise Time	V <sub>DD</sub> =-50V, V <sub>GS</sub> =-10V, R <sub>G</sub> =6Ω I <sub>D</sub> =-15A	---	15	25	pF
T <sub>d(off)</sub>	Turn-Off Delay Time		---	1300	1950	
T <sub>f</sub>	Fall Time		---	340	500	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-50V, V <sub>GS</sub> =0V, F=1MHz	---	12	20	pF
C <sub>oss</sub>	Output Capacitance		---	12	20	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	12	20	

**Drain-Source Diode Characteristics and Maximum Ratings**

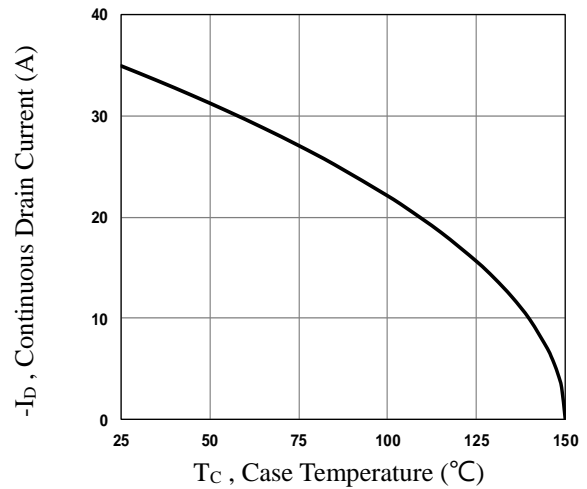
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-35	A
I <sub>SM</sub>	Pulsed Source Current		---	---	-70	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>R</sub> =-100V, I <sub>S</sub> =-10A	---	170	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=100A/μs, T <sub>J</sub> =25°C	---	540	---	nC

Note :

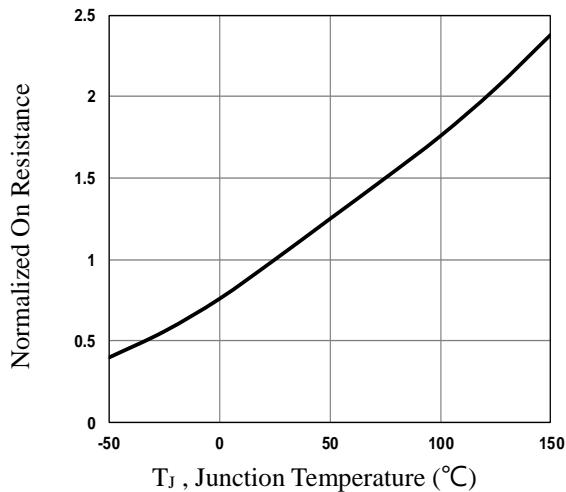
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=-50V, V<sub>GS</sub>=-10V, L=0.1mH, I<sub>AS</sub>=-60A., Starting T<sub>J</sub>=25°C
3. Essentially independent of operating temperature.



**Fig.1 Typical Output Characteristics**



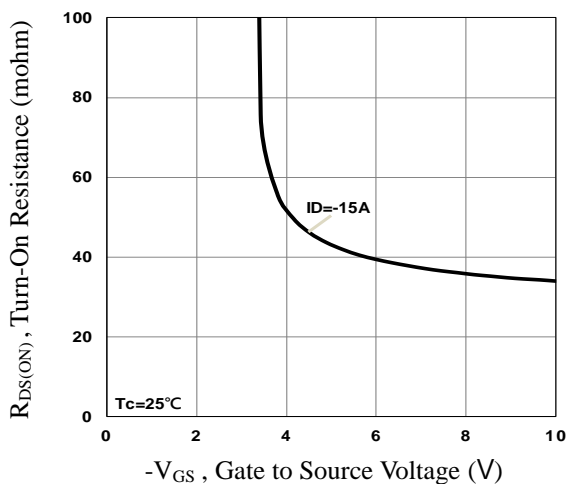
**Fig.2 Continuous Drain Current vs. T<sub>c</sub>**



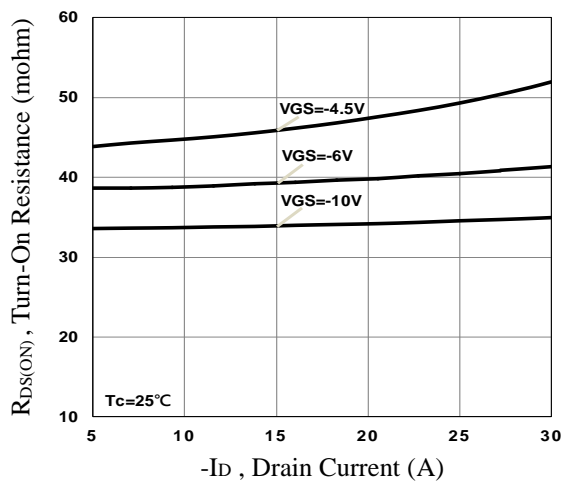
**Fig.3 Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>**



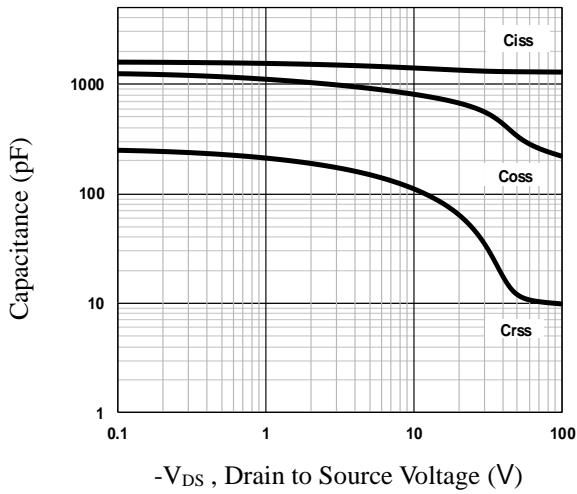
**Fig.4 Normalized V<sub>th</sub> vs. T<sub>J</sub>**



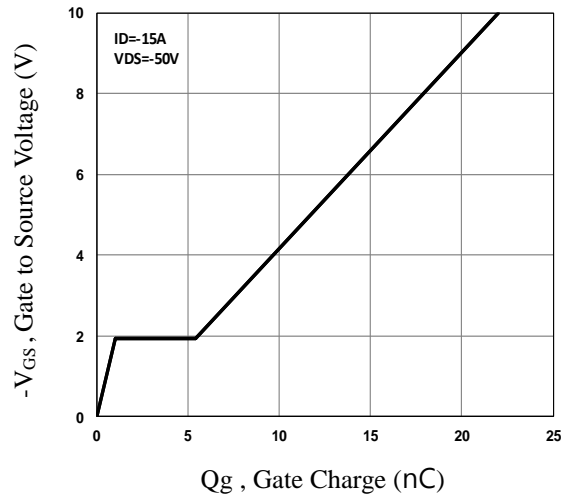
**Fig.5 Turn-On Resistance vs. V<sub>GS</sub>**



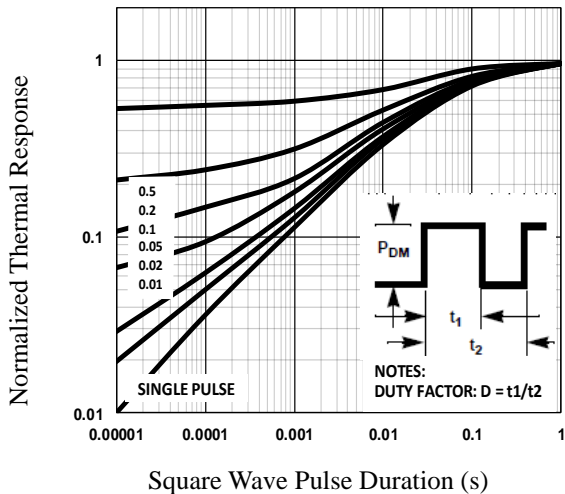
**Fig.6 Turn-On Resistance vs. I<sub>D</sub>**



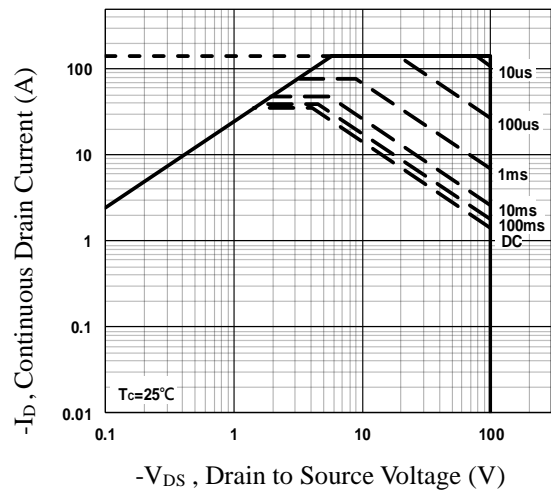
**Fig.7 Capacitance Characteristics**



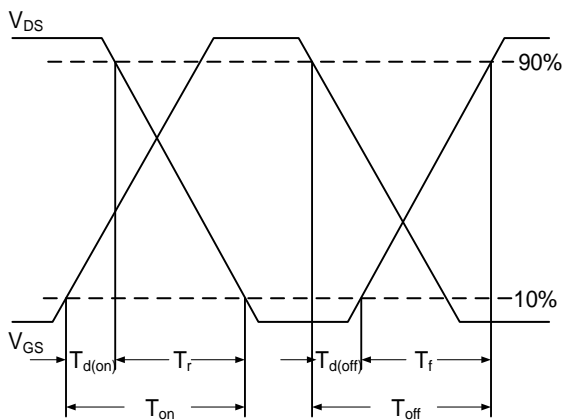
**Fig.8 Gate Charge Characteristics**



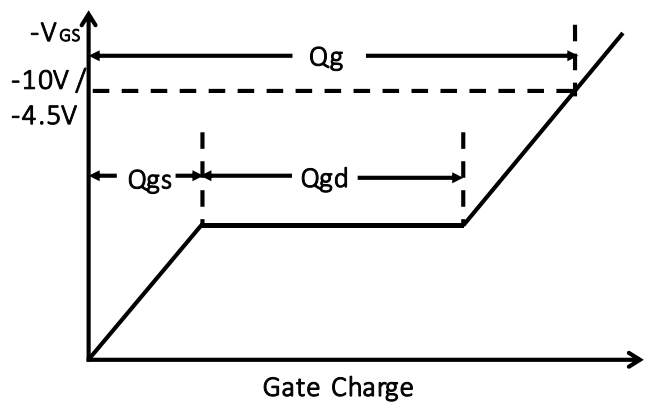
**Fig.9 Normalized Transient Impedance**



**Fig.10 Maximum Safe Operation Area**

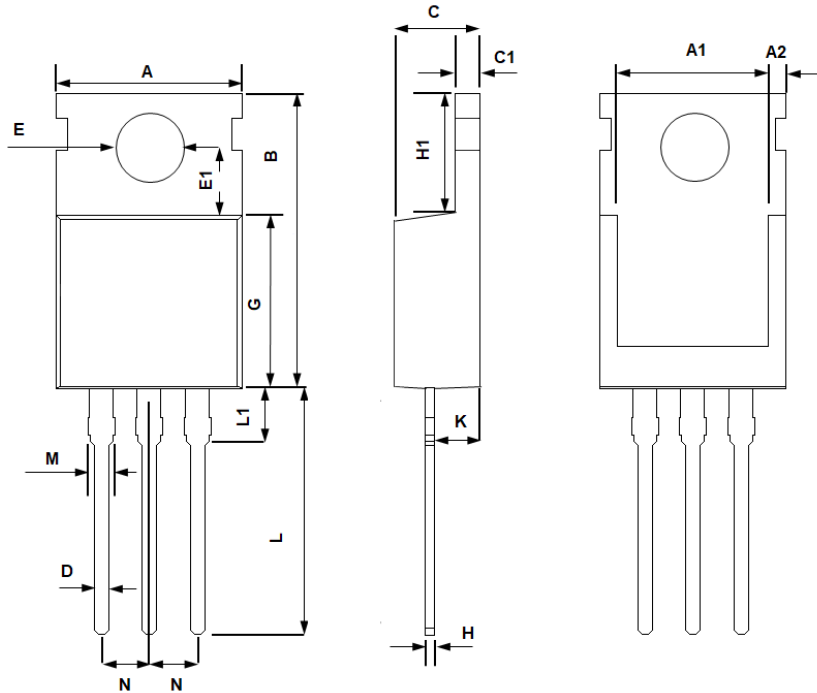


**Fig.11 Switching Time Waveform**



**Fig.12 Gate Charge Waveform**

## TO220 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.400	9.700	0.409	0.382
A1	8.900	7.400	0.350	0.291
A2	1.400	0.800	0.055	0.031
B	16.500	14.500	0.650	0.571
C	4.750	4.200	0.187	0.165
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	4.000	3.300	0.157	0.130
E1	3.800	3.400	0.150	0.134
G	9.400	8.400	0.370	0.331
H	0.600	0.200	0.024	0.008
H1	6.850	6.200	0.270	0.244
K	2.850	2.100	0.112	0.083
L	14.000	12.500	0.551	0.492
L1	4.000	2.700	0.157	0.106
M	1.750	1.100	0.069	0.043
N	2.640	2.440	0.104	0.096